

CPL-WB-00C2

Wide band directional coupler with ISO port

Features

- \blacksquare 50 Ω nominal input / output impedance
- Wide operating frequency range (824 MHz to 2170 MHz)
- Low Insertion Loss (< 0.2 dB)
- 34 dB typical coupling factor
- High directivity (typical 25 dB)
- High ESD robustness (IEC 61000-4-2 Level 4)
- Flip-Chip package
- Small footprint: 1700 x 1200 µm

Benefits

- Very low profile (< 690 µm thickness)</p>
- Lead-free package
- High RF performance
- RF module size reduction

Applications

- Quad band power amplifier module
- Quad band front end module
- GSM / WCDMA mobile phone

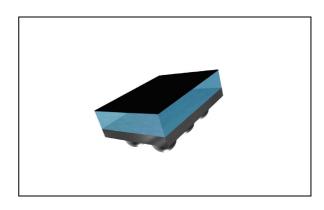
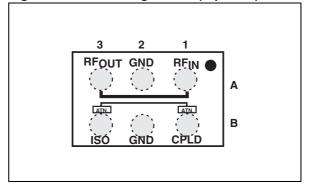


Figure 1. Pin configuration (top view)



Description

The CPL-WB-00 is a wide band directional coupler designed to measure RF antenna output power in GSM / WCDMA applications. This CPL has been customized for wide band operating frequencies (EGSM and CELL, PCS, DCS, WCDMA Band I) with less than 0.2 dB insertion losses in the transmit bandwidth (824 MHz to 1980 MHz).

The CPL-WB has been designed using STMicroelectronics IPD (integrated passive device) technology on non conductive glass substrate to optimize RF performance. The device is delivered 100% tested in tape and reel.

www.Data Characteristics CPL-WB-00C2

1 Characteristics

Table 1. Absolute maximum rating (limiting values)

Symbol	Dovometov	Value			Unit
	Parameter		Тур	Max	Offic
P _{IN}	Input Power RF _{IN}			35	dBm
V _{ESD (IEC)}	ESD ratings IEC 61000-4-2 (C = 150 pF, R = 330 Ω , 10 shots with both polarities and each condition, cumulative method) RF _{IN} , RF _{OUT} , air discharge RF _{IN} , RF _{OUT} , contact discharge	±15 ±8			kV kV
V _{ESD (HBM)}	Human body model, JESD22-A114-B, All I/O	2			kV
V _{ESD (MM)}	Machine model, JESD22-A115-A, All I/O	100			V
V _{ESD (CDM)}	Charge device model, JESD22-C101-C, All I/O	500			V
T _{OP}	Operating temperature	-30		+85	ºC

Table 2. Electrical characteristics ($T_{amb} = 25 \, ^{\circ}C$) - impedances

Symbol	Parameter	Value			Unit
	Parameter		Тур	Max	Unit
Z _{OUT}	Nominal output impedance		50		Ω
Z _{IN}	Nominal input impedance		50		Ω
Z _{CPLD}	Nominal coupling impedance		50		Ω
Z _{OUT}	Nominal ISO impedance		50		Ω

Table 3. Electrical characteristics (T_{amb} = 25 °C) - RF Performance

Symbol	Parameter	Test condition	Value			Unit
		rest condition	Min	Тур	Max	J.III
T _{OP}	Operating temperature		-30		+85	°C
f	Frequency range (bandwidth)		824		1980	MHz
ΙL	Insertion loss in bandwidth	From 824 MHz to 2170 MHz		0.1	0.2	dB
R _L	Return loss in bandwidth	From 824 MHz to 2170 MHz	15			dB
CPLD	Coupling factor (including attenuator)	From 824 MHz to 915 MHz	35		39	dB
		From 1710 MHz to 1980 MHz	28		33	dB
Ripple	Coupling ripple in individual band	(824 to 849 MHz) (880 to 915 MHz) (1710 to 1785 MHz) (1850 to 1910 MHz)(1920 to 1980 MHz)			0.5	dB
DIR	Coupler directivity	From 824 MHz to 1980 MHz	20	25		dB

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www.Data CPL-WB-00C2 Characteristics

1.1 RF measurement (on reference evaluation board)

Measurements done on reference evaluation board under 50 Ω , de-embedding at CPL00 bumps.

Figure 2. Insertion loss

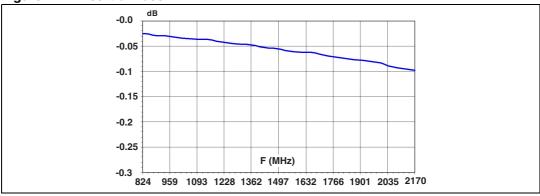


Figure 3. Coupling and isolation

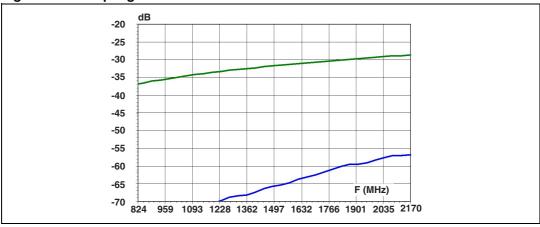
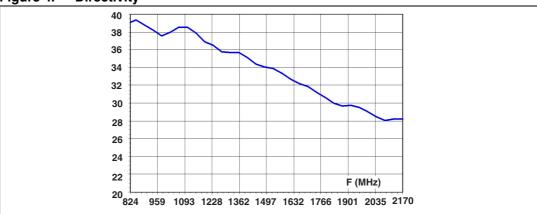


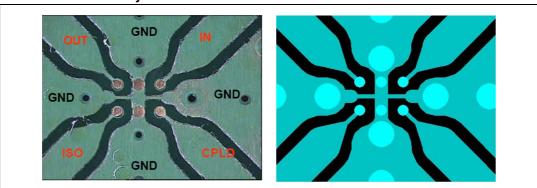
Figure 4. Directivity



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2 Reference evaluation board

Figure 5. CPW lines (W = 850 μ m with gap to gnd = 260 μ m) on top layer + GND on bottom layer



- Material: 2 layers FR4 with solder mask on top and bottom layer
- Substrate thickness: 0.8 mm
- Line lengths: 10.2 mm
- Extension values on short line measurement: 102 ps
- Through insertion loss: 0.20 dB @ 1 GHz , 0.24 dB@ 2 GHz

www.Data CPL-WB-00C2 Package information

3 Package information

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at www.st.com.

Figure 6. Package dimensions

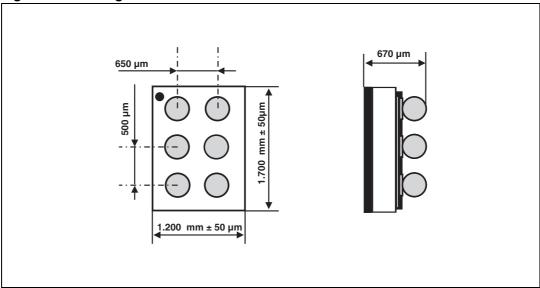


Figure 7. Footprint

Copper pad Diameter:
250 μm recommended, 300 μm max

Solder stencil opening: 330 μm

Solder mask opening recommendation: 340 μm min for 300 μm copper pad diameter

Solder mask opening recommendation: 340 μm min for 300 μm copper pad diameter

Figure 8. Marking

Dot, ST logo

xx = marking

z = manufacturing location
yww = datecode
(y = year
ww = week)

X X Z

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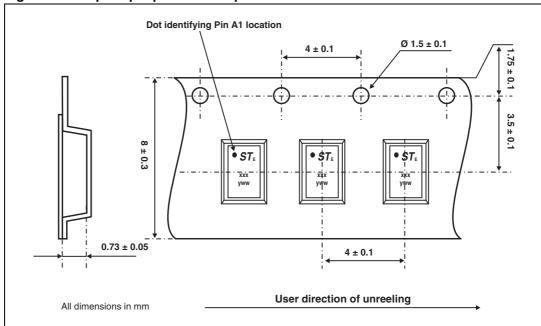


Figure 9. Flip Chip tape and reel specifications

Note: More information is available in the application note:

AN1235: "Flip Chip: package description and recommendations for use"

www.Data CPL-WB-00C2 Ordering information

4 Ordering information

Table 4. Ordering information

Order code	Marking	Base qty	Delivery mode
CPL-WB-00C2	RE 5000 Tape and red		Tape and reel

5 Revision history

Table 5. Document revision history

Date	Revision	Changes
02-Oct-2008	1	Initial release.

www.DataSheet4U.com

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